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Fischer et al.

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[54] **METHOD FOR COATING A SUBSTRATE WITH A COATING SOLUTION**

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[52] U.S. Cl. **427/240; 427/385.5; 427/231**

[58] Field of Search **427/240, 385.5; 437/231**

[56] **References Cited**

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[57] **ABSTRACT**

A method for coating a substrate with a coating solution. In a first step (31), a semiconductor wafer is placed on a turntable. In a second step (32), the substrate is spun at a high speed and a coating solution is dispensed onto the substrate. In a third step (33), the turntable is spun at a low speed and additional coating solution is dispensed onto the substrate.

16 Claims, 2 Drawing Sheets

